



US00D888000S

(12) **United States Design Patent**
Lim

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- (54) **CASE FOR A CIRCUIT BOARD**
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- (**) Term: **15 Years**
- (21) Appl. No.: **29/681,624**
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(30) **Foreign Application Priority Data**

Aug. 29, 2018 (KR) 30-2018-0040307

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**

(58) **Field of Classification Search**
USPC D13/182, 184, 199; D3/201, 272, 273,
D3/274, 303; D10/21, 46, 24, 25, 104.1;
D9/414, 432
CPC H05K 1/00; H05K 5/00; H05K 5/0004;
H05K 5/0008; H05K 5/0091; H05K 5/03;
H05K 5/04; H05K 7/20; H05K 7/00;
H05K 7/005
See application file for complete search history.

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(57) **CLAIM**

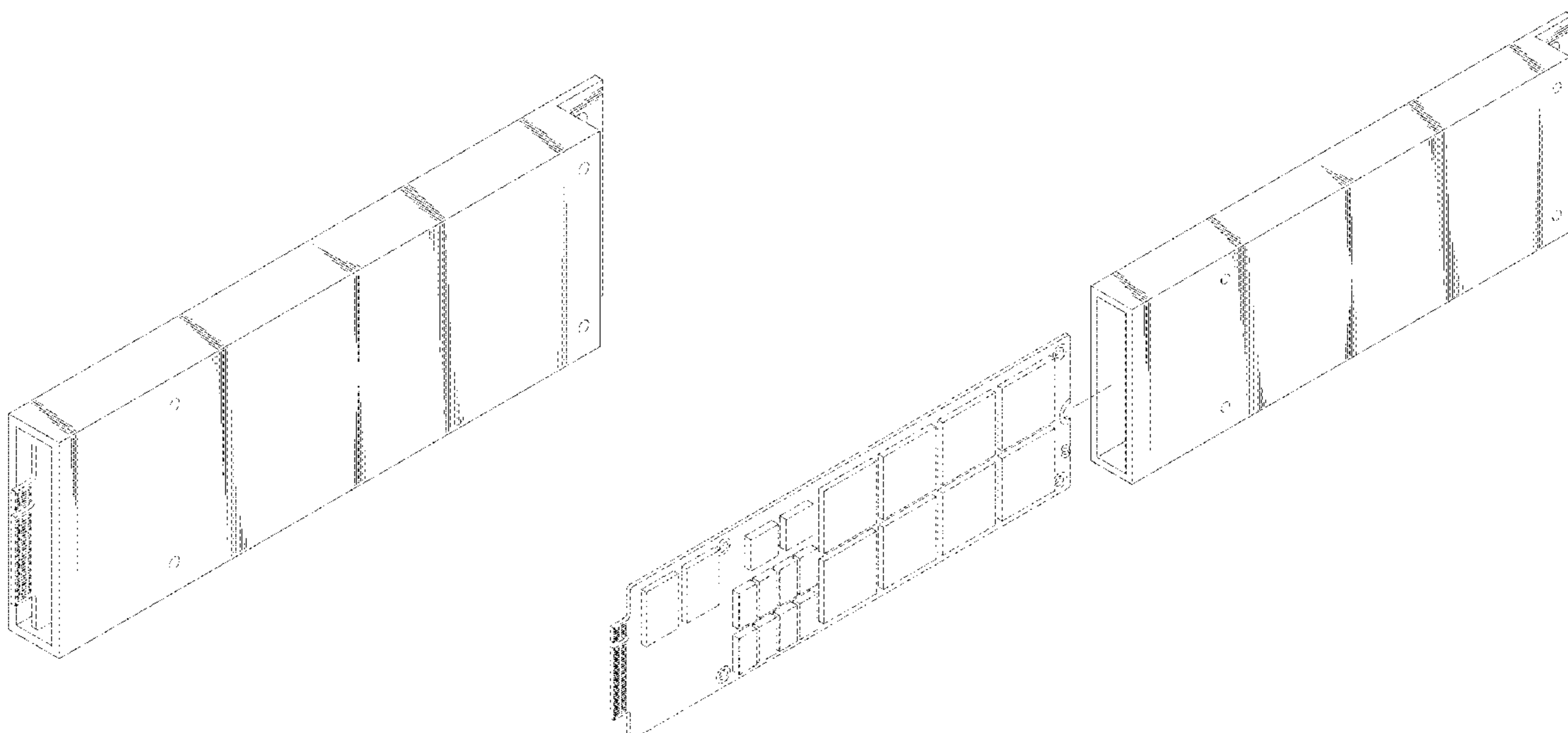
The ornamental design for a case for a circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a case for a circuit board showing our new design;
FIG. 2 is a front elevation view thereof;
FIG. 3 is a rear elevation view thereof;
FIG. 4 is a left side elevation view thereof;
FIG. 5 is a right side elevation view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof; and,
FIG. 8 is a perspective view of a case for a circuit board shown in a used condition with a circuit board shown in broken lines.

The broken lines are for environmental purposes only and form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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FIG. 1

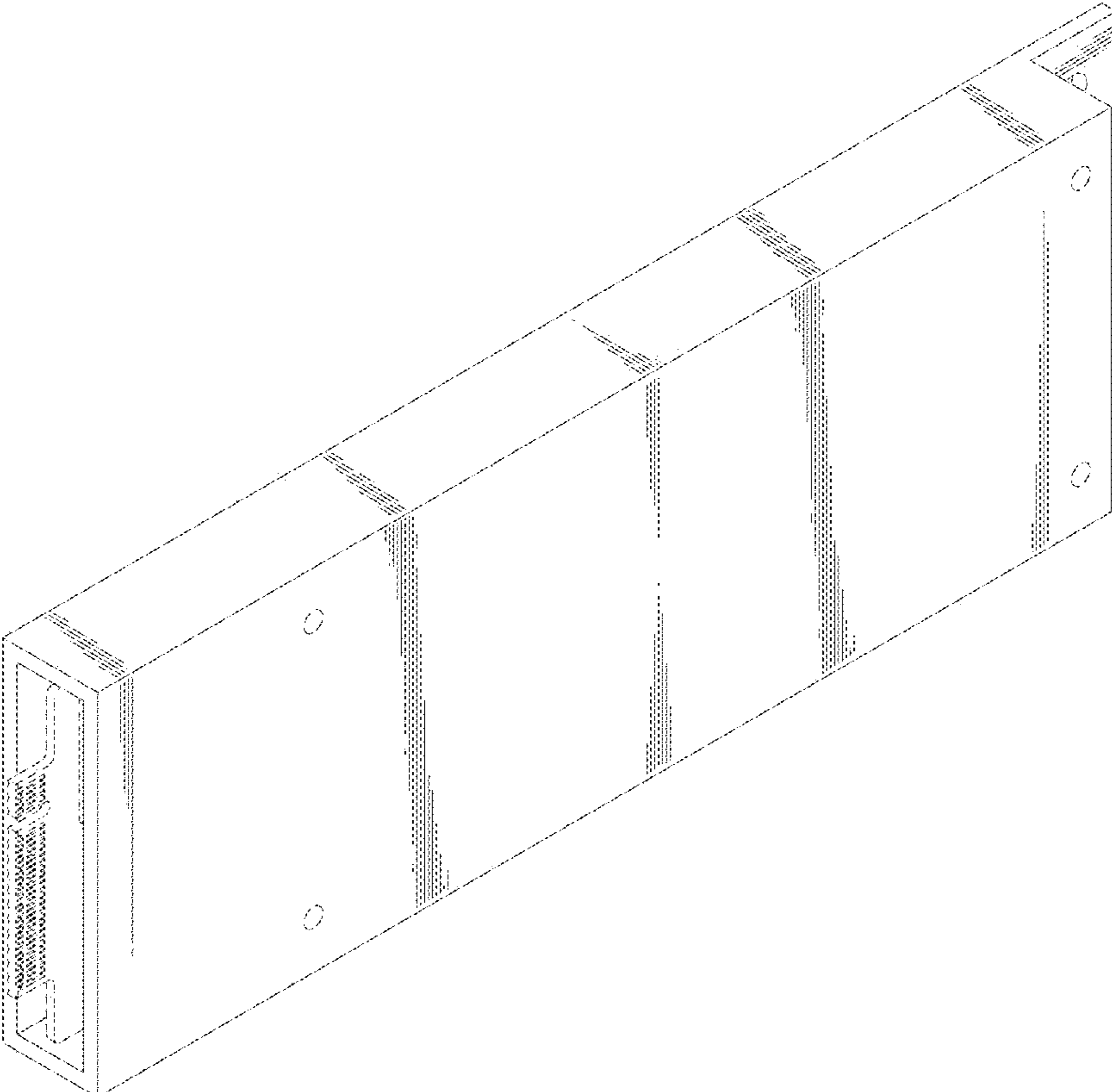


FIG. 2

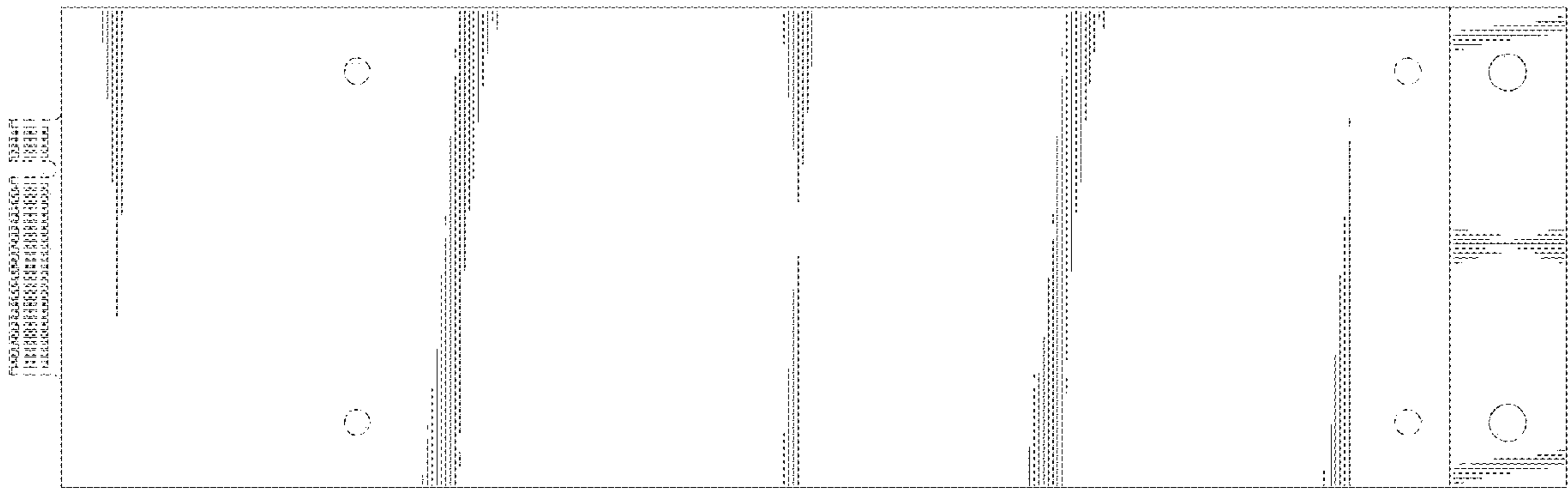


FIG. 3

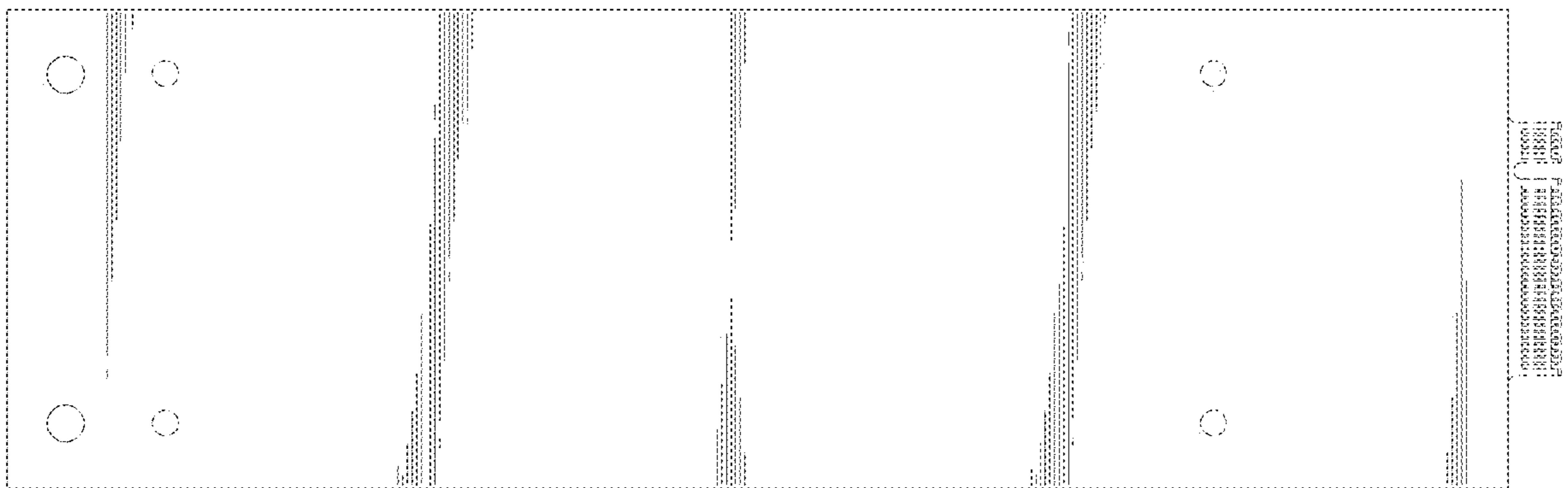


FIG. 4

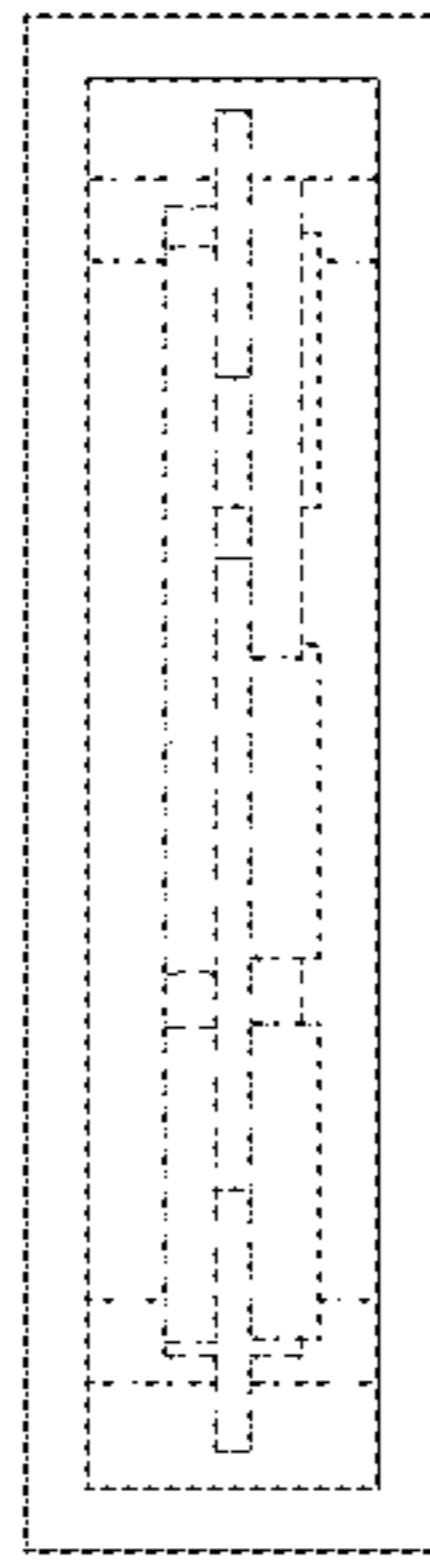


FIG. 5

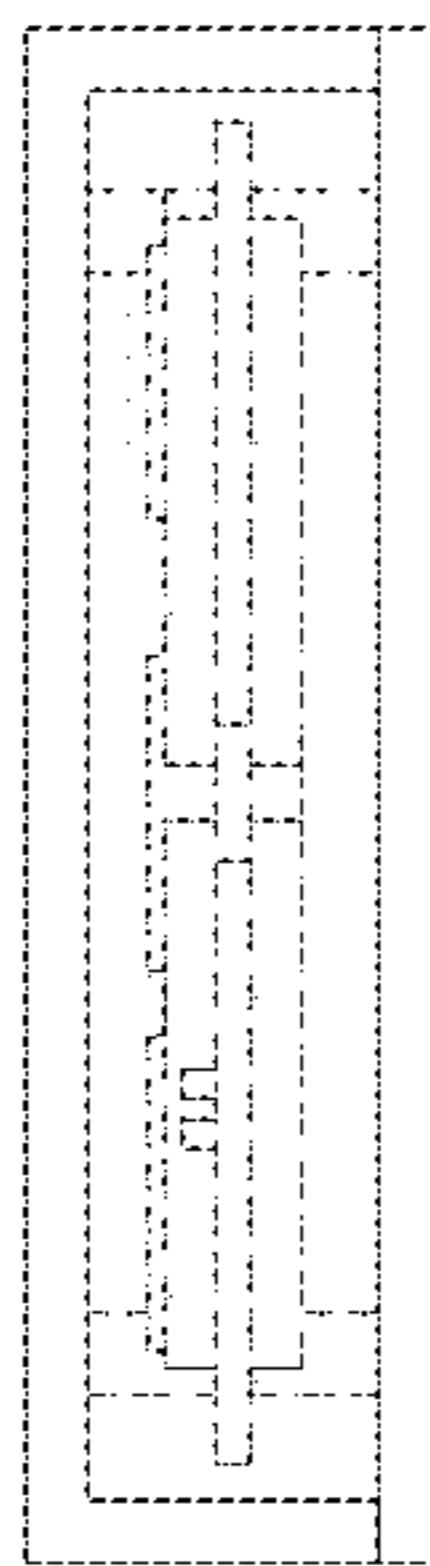


FIG. 6

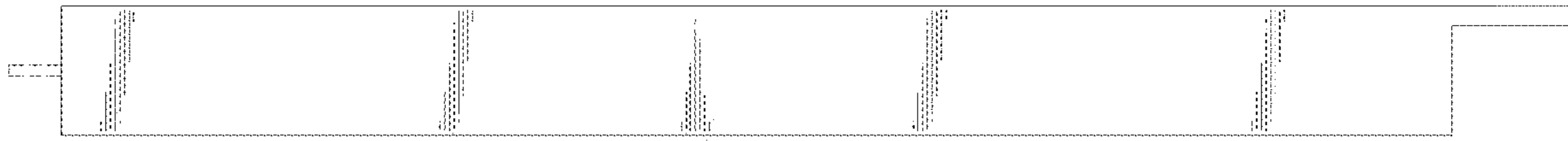


FIG. 7



FIG. 8

